PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		MDG/18/10548
1.3 Title of PCN ASE Kaohsiung (Taiwan) additional source for LQFP 7x7 & LQFP 10x10 extended lister products		ASE Kaohsiung (Taiwan) additional source for LQFP 7x7 & LQFP 10x10 extended listed products
1.4 Product Category LQFP 7x7 & LQFP 10x10 listed products		LQFP 7x7 & LQFP 10x10 listed products
1.5 Issue date 2018-12-12		2018-12-12

2. PCN Team		
2.1 Contact supplier	2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO	
2.1.2 Phone	+1 5148333778	
2.1.3 Email	frank.schifano@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung Taiwan

4. Description of change		
	Old	New
4.1 Description	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC) - ST Muar Malaysia - Amkor ATP Philippines	Back-end sources: - Stats ChipPAC Jiangyin China (JSCC) - ST Muar Malaysia - Amkor ATP Philippines - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN10548 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Lead color and surface finish change depending on leadfinishing. Package darkness changes depending on molding compound. Pin1 identifier can change in terms of form and positioning. Marking position and size could be different upon assembly site, without any loss of information.	

5. Reason / motivation for change	
5.1 Motivation Due to the success on the market of STM8L & STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to decide to extra capacity.	
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change		
6.1 Description	Change is visible through assembly traceability plant, in the marking: - "GQ" and "GH" for Stats ChipPAC China - "9H" for ST Muar Malaysia - "7B" for Amkor ATP Philippines - "AA" for ASE Kaohsiung Taiwan Please refer to PCN 10548 – Additional information attached document.	

7. Timing / schedule	
7.1 Date of qualification results	2018-12-10
7.2 Intended start of delivery	2019-03-10

7.3 Qualification	sample available?
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Upon Request

8. Qualification / Validation			
8.1 Description 10548 MDG-MCD-RER1810 PCN10548 ASE Kaohsiung additional source for LQFP 7x7_10x10_14x14_20x20- reliability plan.pdf			
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-12-12

9. Attachments (additional documentations)

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10548 Public product.pdf 10548 MDG-MCD-RER1810 PCN10548 ASE Kaohsiung additional source for LQFP 7x7_10x10_14x14_20x20- reliability plan.pdf 10548 PCN10548_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F100RBT6B	
	STM32F103RCT6	
	STM32F103RGT6	
	STM32F405RGT6	
	STM32L151RET6TR	

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